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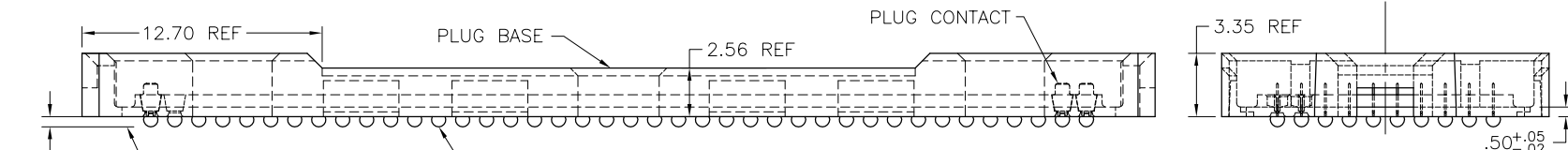
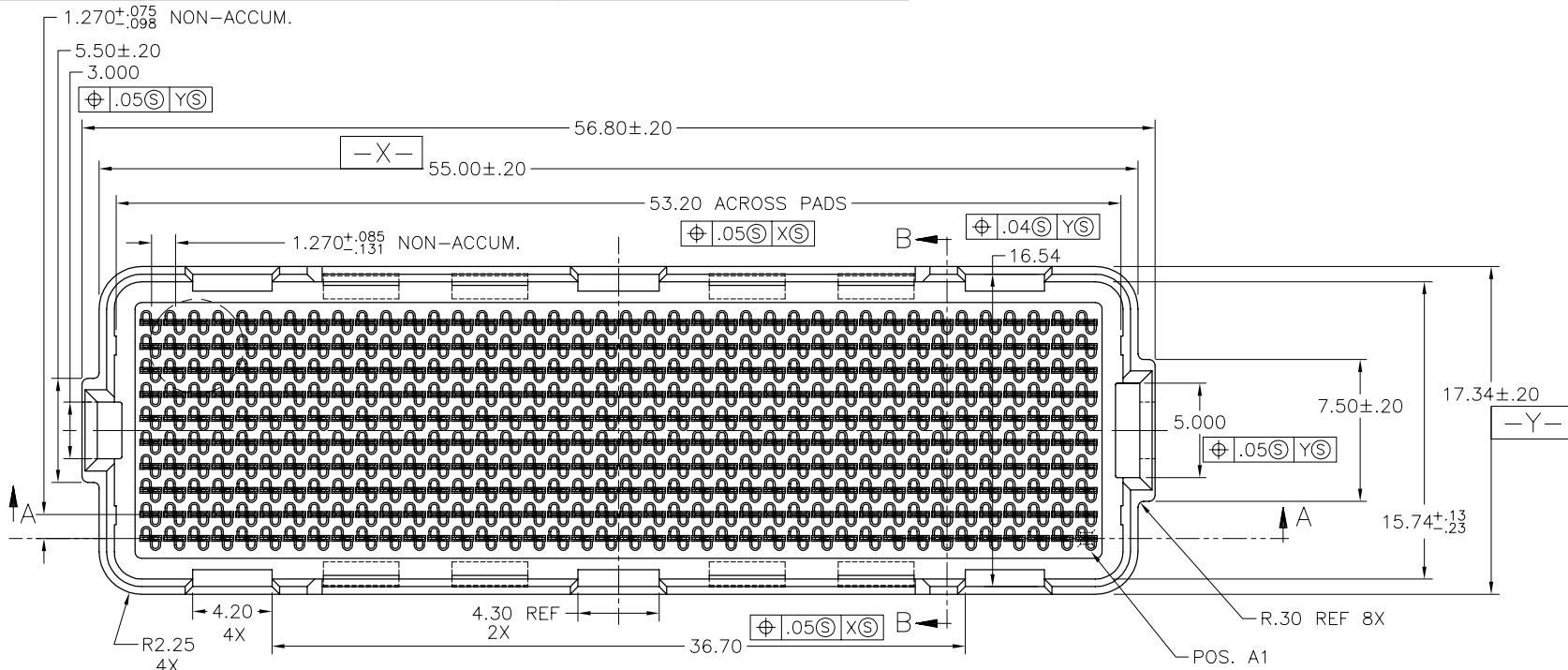
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1 | 2

3 |

4

PRODUCT NUMBER	(SHOWN BELOW)	SOLDER BALL MATERIAL
84739-001	.000" (.000mm) TO .010" (.254mm)	EUTECTIC SnPb
84739-001LF	.000" (.000mm) TO .010" (.254mm)	SnAgCu LEAD FREE (6)(7)



.54 SEE NOTE 5.

SEE TABLE

SOLDER BALLS  
NOTE 2

	φ.30	X	Y
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CONFIDENTIAL: INTEL INTERNAL USE ONLY SEE NOTE 3.

mat'l. code	SEE NOTE 1	surface	ASME Y14.5 ✓	tolerance	ASME Y14.5	projection		product family	MEG-ARRAY
ltr	ec'n no	dr	date	tolerances unless otherwise specified		angles	X*3	title	0mm PLUG ASSY 10 X 40 = 400 POS.
A	V81068	DRW	10.7.98	linear	.XX*.13	0° ±2'	XXX*.051		
B	V90417	DRW	3.5.99	scale	3:1			sheet	1 of 3
C	V00181	HLJ	09.07.00	enr	M. HAHN	9.21.98	type	CUSTOMER Drawing	size
D	V04-0940	VS	12/11/04	chr	M. HAHN	9.21.98			
E	V05-0825	DAI	09/29/05	appd	M. HAHN	9.21.98			
F	V06-0046	DAI	01/24/06	sheet	1	2	3	84739	A4
G	V06-0560	LP	2006/07/14	index	1	2	3		

WAS SK-40415

form: A4mmXLC

1 |

2 |

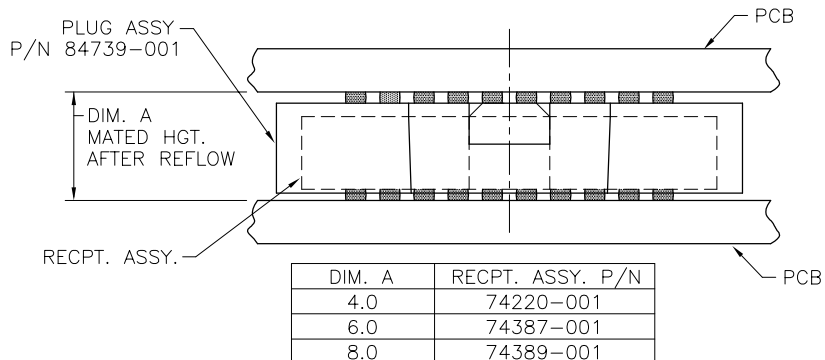
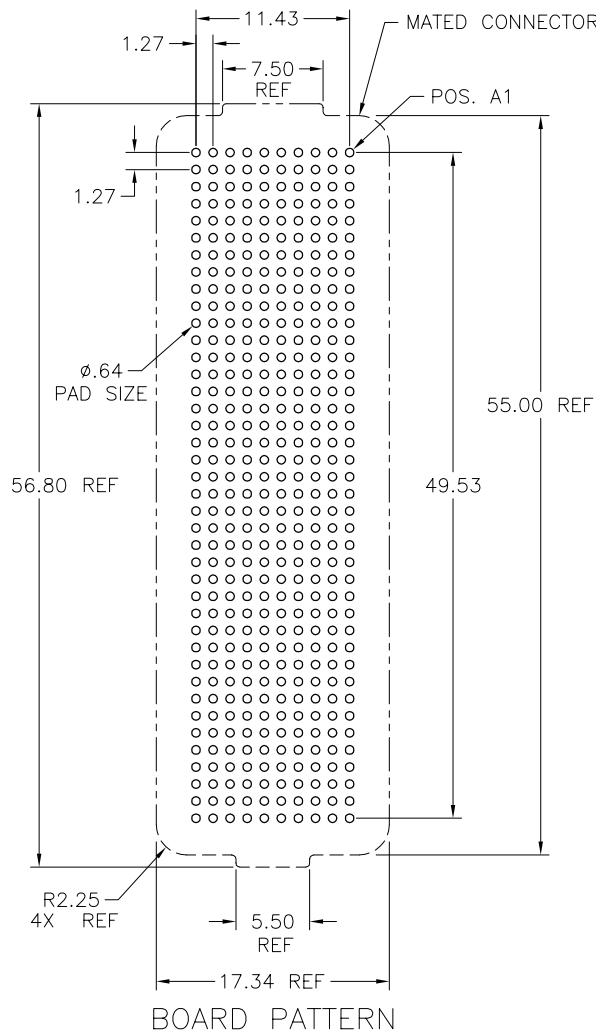
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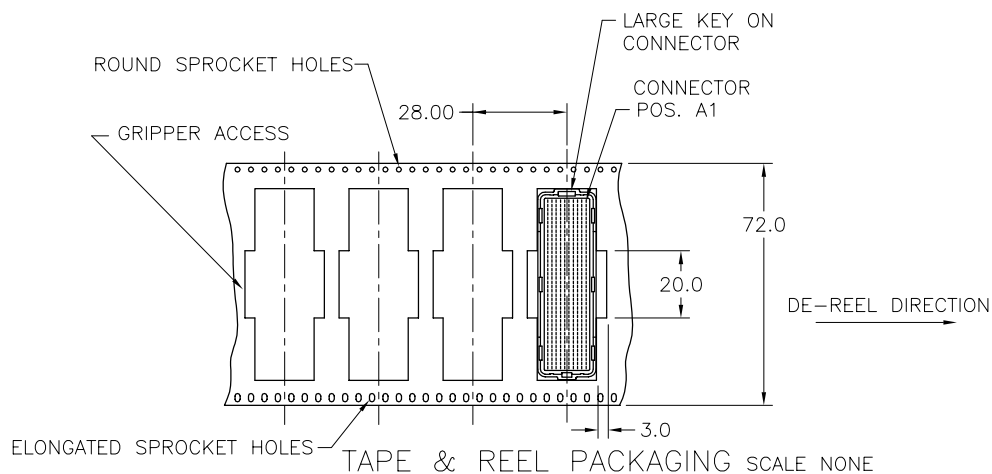
PDM: Rev:G

STATUS Released

Printed: Jul 31, 2006

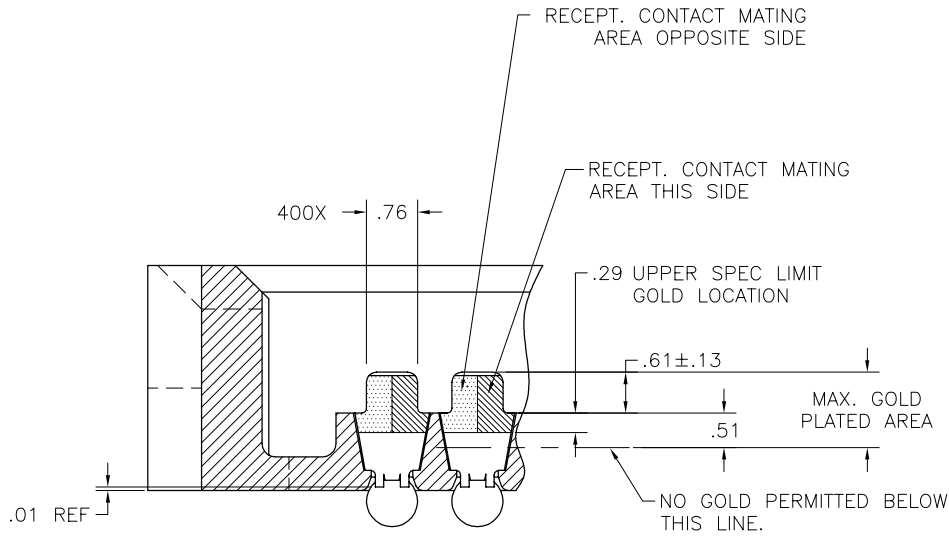


MATED HEIGHT AFTER REFLOW IS BASED ON Ø .64mm PAD (METAL-DEFINED) AND .13mm SOLDER PASTE STENCIL THICKNESS.

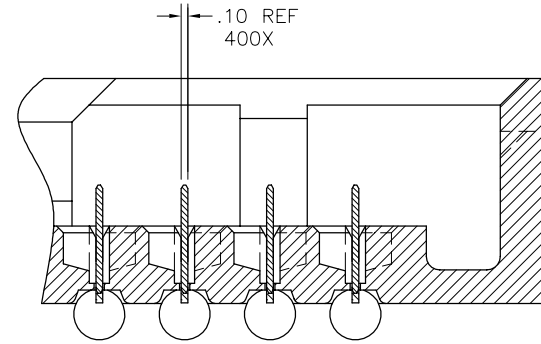


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mat'l. code SEE NOTE 1		surface ASME Y14.5 ✓	tolerance ASME Y14.5	projection ⊕	product family MEG-ARRAY
ltr	ecr no	dr	date	tolerances unless otherwise specified	title
G				angles X ±3 XX ±13 XXX ±051	0mm PLUG ASSY 10 X 40 = 400 POS.
				0° ±2'	scale 2:1
		dr	D.WAUGHEN	9.21.98	FCI
		enr	M.HAHN	9.21.98	dwg no
		chr	M.HAHN	9.21.98	sheet 2 of 3
		appd	M.HAHN	9.21.98	84739
sheet index	revision sheet				size A4
					type CUSTOMER Drawing



SECT. A-A



SECT. B-B  
ROTATED 90° C.W.

**NOTES:**

1. **MAT'L:**

**HOUSING:** NATURAL LCP (GRADE PROPRIETARY).

**CONTACT:** CUPPER-NICKEL ALLOY C72500.

**PLATING:**

**CONTACT:** 15-40u"/.38-1.02um Au OVER

30-120u"/.76-3.05um Ni.

SOLDER BALL: (SEE TABLE ON SHEET1)

EUTECTIC SnPb OR LEAD FREE

95.5Sn/4Ag/0.5Cu

2. SOLDER BALLS WILL NOT BE PERFECT SPHERICAL SHAPE DUE TO REFLOW ATTACHMENT. NOMINAL INITIAL SOLDER BALL  $\phi$ .76 (.030").

3. DRAWING NO. 84740 TO BE USED FOR INTEL CUSTOMERS (OEM).

4. REFER TO 07-747 INTEL PROCUREMENT SPEC.

5. SOLDER BALL HEIGHT TOLERANCE PENDING FINAL AGREEMENT.

6. FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION GS-20-033 LEAD FREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS DUE TO A HIGHER REFLOW TEMPERATURE. LEAD FREE PRODUCT IS THEREFORE NOT BACKWARDS COMPATIBLE WITH LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE FCI APPLICATION SPECIFICATION

7. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008 PRODUCT MEETING THIS DIRECTIVE IS IDENTIFIED IN THE LOT CODE NUMBER MARKED ON EACH PART BY HAVING AN "X" IN THE SEVENTH CHARACTER POSITION

**CONFIDENTIAL: INTEL INTERNAL USE ONLY. SEE NOTE 3.**

mat'l. code SEE NOTE 1		surface ASME Y14.5	tolerance ASME Y14.5	projection 	product family MEG-ARRAY
ltr	ecr no	dr	date	tolerances unless otherwise specified	title
g				angles X*.3	0mm PLUG ASSY.
				line fit .XX*.13	10 X 40 = 400 POS.
				0° ±2'	scale 10:1
		dr	D. WAUGHEN	9.21.98	dwg no 84739 sheet 3 of 3 size A4 type CUSTOMER Drawing
		enr	M. HAHN	9.21.98	
		chr	M. HAHN	9.21.98	
		appd	M. HAHN	9.21.98	
sheet index	revision sheet				